TOSHIBA MP4501

TOSHIBA POWER TRANSISTOR MODULE SILICON NPN EPITAXIAL TYPE (DARLINGTON POWER TRANSISTOR 4 IN 1)

M P 4 5 0 1

HIGH POWER SWITCHING APPLICATIONS.

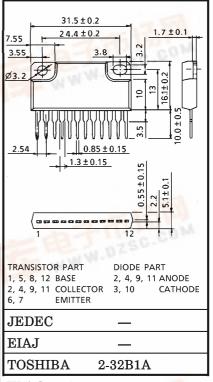
HAMMER DRIVE, PULSE MOTOR DRIVE AND INDUCTIVE LOAD SWITCHING.

- Package with Heat Sink Isolated to Lead (SIP 12 Pin)
- High Collector Power Dissipation (4 Devices Operation) $: P_T = 5W (Ta = 25^{\circ}C)$
- High Collector Current : I_C (DC)=3A (Max.)
- High DC Current Gain: hFE=2000 (Min.) (VCE=2V, IC=1.5A)
- Diode Included for Absorbing Fly-Back Voltage.

MAXIMUM RATINGS (Ta = 25°C)

STIC	SYMBOL	RATING	UNIT	
Collector-Base Voltage			V	
Collector-Emitter Voltage			V	
- 63-5	$V_{\rm EBO}$	6	V	
DC	$I_{\mathbf{C}}$	3	_	
Pulse	ICP	6	A	
ent	I_{B}	0.5	A	
Collector Power Dissipation (1 Device Operation)			w	
Ta=25°C	Pm	5.0	w	
Tc = 25°C	13.60	25		
Isolation Voltage			°C	
Junction Temperature			°C	
Storage Temperature Range			°C	
	DC Pulse ent ation Ta=25°C Tc=25°C	$\begin{array}{c c} & V_{CBO} \\ & V_{CEO} \\ \hline & V_{EBO} \\ \hline DC & I_{C} \\ \hline Pulse & I_{CP} \\ \hline ent & I_{B} \\ \hline ation & P_{C} \\ \hline T_{c}=25^{\circ}C & \\ \hline V_{Isol} \\ \hline T_{j} & \\ \hline \end{array}$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	

INDUSTRIAL APPLICATIONS Unit in mm



Weight: 6.0g

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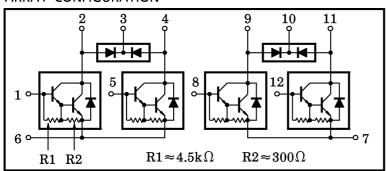
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ARRAY CONFIGURATION



THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance of Junction to Ambient (4 Devices Operation, Ta=25°C)	$\Sigma R_{ ext{th (j-a)}}$	25	°C/W
Thermal Resistance of Junction to Case (4 Devices Operation, Tc=25°C)	$\Sigma m R_{th (j-c)}$	5.0	°C/W
Maximum Lead Temperature for Soldering Purposes (3.2mm from Case for 10s)	$ ext{T}_{ ext{L}}$	260	°C

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHAR.	ACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Collector C	ut-off Current	I_{CBO}	$V_{\rm CB} = 120 { m V}, \; { m I}_{ m E} = 0$		_	10	μ A
Collector C	ut-off Current	ICEO	$V_{CE} = 100V, I_B = 0$	_	_	10	μ A
Emitter Cu	t-off Current	I_{EBO}	$V_{EB} = 6V, I_C = 0$	0.5	_	2.5	mA
Collector-Ba Breakdown		V (BR) CBO	$I_C=1mA$, $I_E=0$	120	_	_	V
Collector-En Breakdown		V (BR) CEO	$I_{C}=10mA, I_{B}=0$	100	_	_	V
DO O A O.	hFE (1)	$V_{CE} = 2V, I_{C} = 1.5A$	2000	_	15000		
DC Current Gain		hFE (2)	$V_{CE}=2V$, $I_{C}=3A$	1000	_	_	
Saturation	Collector-Emitter	V _{CE} (sat)	$I_{C}=1.5A, I_{B}=3mA$		_	1.5	V
Voltage	Base-Emitter	V _{BE} (sat)	$I_{C} = 1.5A, I_{B} = 3mA$	_	_	2.0	V
Transition Frequency		$ m f_{T}$	$V_{ m CE}$ =2V, $I_{ m C}$ =0.5A	_	60	_	MHz
Collector O	utput Capacitance	C_{ob}	$V_{CB} = 10V, I_E = 0, f = 1MHz$	l	30	_	рF
Switching Time	Turn-on Time	ton	I_{B1} OUTPUT I_{B2} INPUT I_{B2} I_{B2} I_{B3}	ı	0.3	_	
	Storage Time	${ m t_{stg}}$	I_{B1} I_{B2} $V_{CC}=30V_{m}$	_	2.0	_	μ s
	Fall Time	tf	$I_{B1} = -I_{B2} = 3mA$, DUTY CYCLE $\leq 1\%$		0.4	_	

EMITTER-COLLECTOR DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Maximum Forward Current	I_{FM}	_	_	_	3	A
Surge Current	I_{FSM}	t=1s, 1 shot	_	_	6	Α
Forward Voltage	$V_{\mathbf{F}}$	$I_F=1A$, $I_B=0$	_	1.2	1.8	V
Reverse Recovery Time	t _{rr}	$I_{F}=3A, V_{BE}=-3V,$	_	1.0	_	μ s
Reverse Recovery Charge	Q_{rr}	$dI_F/dt = -50A/\mu s$		5	_	μC

FLYBACK-DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Maximum Forward Current	$I_{ extbf{FM}}$		_	_	3	A
Reverse Current	$I_{\mathbf{R}}$	$V_R = 120V$	_		0.4	μ A
Reverse Voltage	$v_{ m R}$	$I_R = 100 \mu A$	120	_	_	V
Forward Voltage	$ m V_{f F}$	$I_{\mathbf{F}} = 0.5\mathbf{A}$	_	_	1.8	V

